

SEMICONDUCTOR PACKAGE AND PRODUCTION METHOD

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ABSTRACT OF THE DISCLOSURE

A plurality of semiconductor packages is
collectively fabricated on a wafer in a batch process and
10 the wafer is then diced to obtain discrete semiconductor
packages. The semiconductor package is a stacked body
formed by bonding two or more semiconductor devices.
Each semiconductor device comprises a substrate and a
device pattern formed on a surface of the substrate. The
15 semiconductor devices are stacked in such a fashion that
a device pattern surface of the lower semiconductor
device faces a non-device pattern surface of the
semiconductor device stacked on the same.